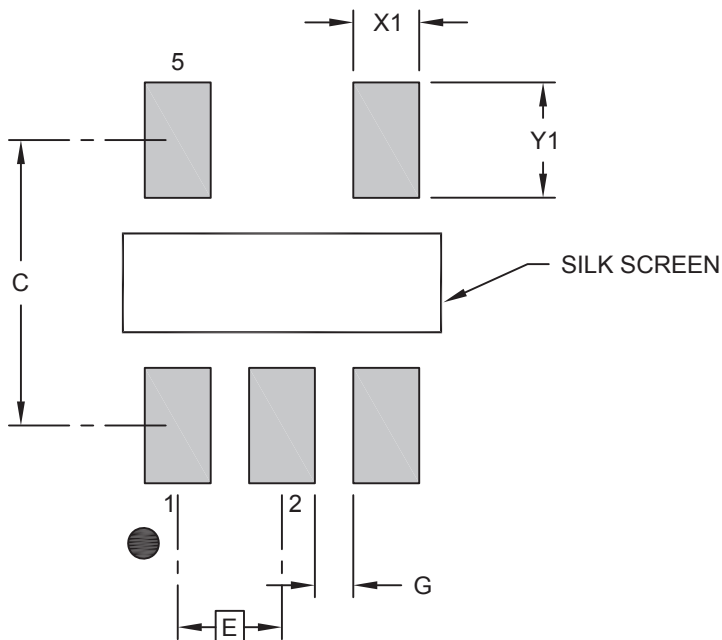


# 5-Lead Plastic Thin Small Outline Transistor (NMB) [TSOT] Atmel Legacy Global Package Code TSZ

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



## RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	C		2.60	
Contact Pad Width (X5)	X1			0.60
Contact Pad Length (X5)	Y1			1.05
Contact Pad to Center Pad (X2)	G	0.20		

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process